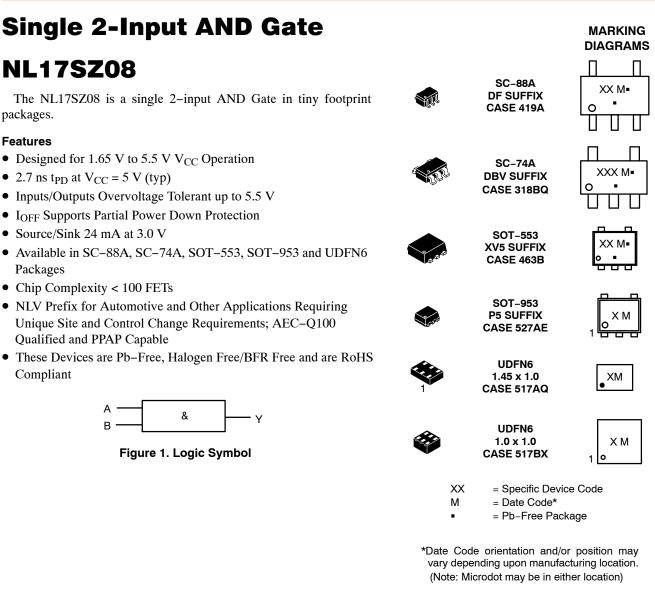
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packages. Features

Packages

Compliant

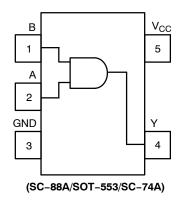
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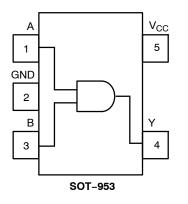


ORDERING INFORMATION

See detailed ordering, marking and shipping information in the package dimensions section on page 7 of this data sheet.

NL17SZ08





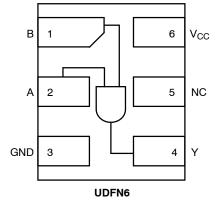


Figure 2. Pinout (Top View)

PIN ASSIGNMENT

(SC-88A/SOT-553/SC-74A)

Pin	Function
1	В
2	А
3	GND
4	Y
5	V _{CC}

PIN ASSIGNMENT (SOT-953)

Function
А
GND
В
Y
V _{CC}

PIN ASSIGNMENT (UDFN)

Pin	Function
1	В
2	A
3	GND
4	Y
5	NC
6	V _{CC}

FUNCTION TABLE

Ing	Output Y = AB	
Α	В	Y
L	L	L
L	Н	L
Н	L	L
Н	Н	Н

MAXIMUM RATINGS

Symbol	Chara	cteristics	Value	Unit
V _{CC}	DC Supply Voltage	(NLV)	-0.5 to +7.0 -0.5 to +6.5	V
V _{IN}	DC Input Voltage	(NLV)	-0.5 to +7.0 -0.5 to +6.5	V
V _{OUT}	DC Output Voltage (NLV)	Active-Mode (High or Low State) Tri-State Mode (Note 1) Power-Down Mode (V _{CC} = 0 V)	-0.5 to V _{CC} + 0.5 -0.5 to +7.0 -0.5 to +7.0	V
	DC Output Voltage	(NL17SZ08P5T5G-L22088 Only)	–0.5 to V _{CC} + 0.5	
	DC Output Voltage	Active-Mode (High or Low State) Tri-State Mode (Note 1) Power-Down Mode (V _{CC} = 0 V)	-0.5 to V _{CC} + 0.5 -0.5 to +6.5 -0.5 to +6.5	
I _{IK}	DC Input Diode Current	V _{IN} < GND	-50	mA
I _{OK}	DC Output Diode Current	V _{OUT} < GND	-50	mA
	DC Output Diode Current	(NL17SZ08P5T5G-L22088 Only)	±50	
I _{OUT}	DC Output Source/Sink Current		±50	mA
I _{CC} or I _{GND}	DC Supply Current per Supply Pin or 0	Ground Pin	±100	mA
T _{STG}	Storage Temperature Range		-65 to +150	°C
ΤL	Lead Temperature, 1 mm from Case for	or 10 secs	260	°C
TJ	Junction Temperature Under Bias		+150	°C
θ_{JA}	Thermal Resistance (Note 2)	SC-88A SC-74A SOT-553 SOT-953 UDFN6	377 320 324 254 154	°C/W
PD	Power Dissipation in Still Air	SC-88A SC-74A SOT-553 SOT-953 UDFN6	332 390 386 491 812	mW
MSL	Moisture Sensitivity		Level 1	-
F _R	Flammability Rating	Oxygen Index: 28 to 34	UL 94 V-0 @ 0.125 in	-
V_{ESD}	ESD Withstand Voltage (Note 3)	Human Body Model Charged Device Model	2000 1000	V
I _{Latchup}	Latchup Performance (Note 4)		±100	mA

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.
Applicable to devices with outputs that may be tri-stated.
Measured with minimum pad spacing on an FR4 board, using 10mm-by-1inch, 2 ounce copper trace no air flow per JESD51-7.
HBM tested to ANSI/ESDA/JEDEC JS-001-2017. CDM tested to EIA/JESD22-C101-F. JEDEC recommends that ESD qualification to EIA/JESD22-A115-A (Machine Model) be discontinued per JEDEC/JEP172A.

4. Tested to EIA/JESD78 Class II.

RECOMMENDED OPERATING CONDITIONS

Symbol	Char	acteristics	Min	Max	Unit
V _{CC}	Positive DC Supply Voltage		1.65	5.5	V
V _{IN}	DC Input Voltage		0	5.5	V
V _{OUT}	DC Output Voltage	Active-Mode (High or Low State) Tri-State Mode (Note 1) Power-Down Mode (V _{CC} = 0 V)	0 0 0	V _{CC} 5.5 5.5	V
	DC Output Voltage	(NL17SZ08P5T5G-L22088 Only)	0	V _{CC}	
T _A	Operating Temperature Range		-55	+125	°C
t _r , t _f	Input Rise and Fall Time (NLV)	$V_{CC} = 3.0 V \text{ to } 3.6 V$ $V_{CC} = 4.5 V \text{ to } 5.5 V$	0 0	100 20	ns/V
	Input Rise and Fall Time	$\begin{array}{l} V_{CC} = 1.65 \; V \; \text{to} \; 1.95 \; V \\ V_{CC} = 2.3 \; V \; \text{to} \; 2.7 \; V \\ V_{CC} = 3.0 \; V \; \text{to} \; 3.6 \; V \\ V_{CC} = 4.5 \; V \; \text{to} \; 5.5 \; V \end{array}$	0 0 0 0	20 20 10 5	

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

DC ELECTRICAL CHARACTERISTICS

			v _{cc}	Т	A = 25°	С	–55°C ≤ T	_A ≤ 125°C	
Symbol	Parameter	Condition	(V)	Min	Тур	Max	Min	Max	Units
VIH	High-Level Input Vol		1.65 to 1.95	$0.75 \times V_{CC}$	-	-	$0.75 \times V_{CC}$	-	V
	and NL17SZ08P5T5	G-L22088	2.3 to 5.5	$0.70 \times V_{CC}$	-	-	$0.70 \times V_{CC}$	-	1
	High-Level Input Vol	tage	1.65 to 1.95	0.65 x V _{CC}	-	-	0.65 x V _{CC}	-	V
			2.3 to 5.5	0.70 x V _{CC}	-	-	0.70 x V _{CC}	-	1
VIL	Low-Level Input Voltage (NLV)		1.65 to 1.95	-	-	$0.25 \times V_{CC}$	-	$0.25 \times V_{CC}$	V
	and NL17SZ08P5T5G-L22088		2.3 to 5.5	-	-	$0.30 \times V_{CC}$	-	$0.30 \times V_{CC}$	
	Low-Level Input Volt	age	1.65 to 1.95	-	-	$0.35 \times V_{CC}$	-	$0.35 \times V_{CC}$	V
			2.3 to 5.5	-	-	$0.30 \times V_{CC}$	-	$0.30 \times V_{CC}$	
V _{OH}	High-Level Output Voltage		1.65 to 5.5 1.65 2.3 2.7 3.0 3.0 4.5	V _{CC} - 0.1 1.29 1.9 2.2 2.4 2.3 3.8	V _{CC} 1.4 2.1 2.4 2.7 2.5 4.0	- - - - -	V _{CC} - 0.1 1.29 1.9 2.2 2.4 2.3 3.8	- - - - -	V
V _{OL}	Low-Level Output Voltage		1.65 to 5.5 1.65 2.3 2.7 3.0 3.0 4.5		- 0.08 0.2 0.22 0.28 0.38 0.38	0.1 0.24 0.3 0.4 0.4 0.55 0.55		0.1 0.24 0.3 0.4 0.4 0.55 0.55	V
I _{IN}	Input Leakage Cur- rent	V _{IN} = 5.5 V or GND	1.65 to 5.5	-	-	±0.1	-	±1.0	μΑ
I _{OFF}	Power Off Leakage Current	V _{IN} = 5.5 V or V _{OUT} = 5.5 V	0	-	-	1.0	-	10	μΑ
	Power Off Leakage Current (NL17SZ08P5T5G– L22088 Only)	V _{IN} = 5.5 V	0	-	-	1.0	-	10	μΑ
I _{CC}	Quiescent Supply Current	$V_{IN} = V_{CC}$ or GND	5.5	-	_	1.0	-	10	μA

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

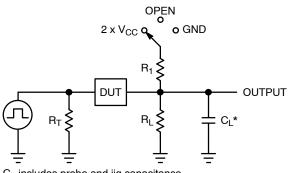
AC ELECTRICAL CHARACTERISTICS

			$V_{CC} \qquad T_{A} = 25^{\circ}C \qquad -55^{\circ}C \le T_{A} \le 125^{\circ}$		T _A = 25°C		_A ≤ 125°C		
Symbol	Parameter	Condition	(V)	Min	Тур	Max	Min	Max	Units
t _{₽LH} ,	Propagation Delay, A to Y	R_L = 1 MΩ, C_L = 15 pF	1.65 to 1.95	-	6.3	12	-	12.7	ns
t _{PHL}	(Figures 3 and 4)	R_L = 1 M Ω , C_L = 15 pF	2.3 to 2.7	-	3.4	7.0	-	7.5	
		R_L = 1 M Ω , C_L = 15 pF	3.0 to 3.6	-	2.6	4.7	-	5.0	
		R_L = 500 Ω , C_L = 50 pF		-	3.3	5.2	-	5.5	
		R_L = 1 M Ω , C_L = 15 pF	4.5 to 5.5	-	2.2	4.1	-	4.4	
		R_L = 500 Ω , C_L = 50 pF		-	2.7	4.5	-	4.8	

CAPACITIVE CHARACTERISTICS

Symbol	Parameter	Condition	Typical	Units
C _{IN}	Input Capacitance	V_{CC} = 5.5 V, V_{IN} = 0 V or V_{CC}	2.5	pF
C _{OUT}	Output Capacitance	V_{CC} = 5.5 V, V_{IN} = 0 V or V_{CC}	2.5	pF
C _{PD}	Power Dissipation Capacitance (Note 5)	10 MHz, V _{CC} = 3.3 V, V _{IN} = 0 V or V _{CC} 10 MHz, V _{CC} = 5.5 V, V _{IN} = 0 V or V _{CC}	9 11	pF

5. C_{PD} is defined as the value of the internal equivalent capacitance which is calculated from the operating current consumption without load. Average operating current can be obtained by the equation: $I_{CC(OPR)} = C_{PD} \bullet V_{CC} \bullet f_{in} + I_{CC}$. C_{PD} is used to determine the no–load dynamic power consumption; $P_D = C_{PD} \bullet V_{CC}^2 \bullet f_{in} + I_{CC} \bullet V_{CC}$.

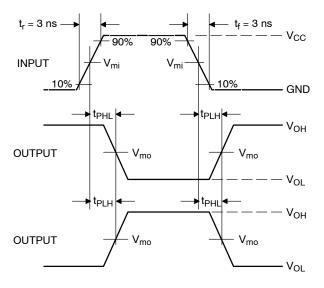


Position	tch C _L , pF tion		R ₁ , Ω
Open	See AC Character	istics Tal	ble
$2 \times V_{CC}$	50	500	500
GND	50	500	500
	Open 2 x V _{CC}	Open See AC Character 2 x V _{CC} 50 GND 50	OpenSee AC Characteristics Tat2 x V _{CC} 50GND5050500

X = Don't Care

 C_L includes probe and jig capacitance R_T is Z_{OUT} of pulse generator (typically 50 $\Omega)$ f = 1 MHz

Figure 3. Test Circuit



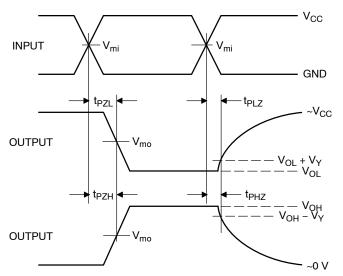


Figure 4. Switching Waveforms

		Vm		
V _{CC} , V	V _{mi} , V	t _{PLH} , t _{PHL}	t _{PZL} , t _{PLZ} , t _{PZH} , t _{PHZ}	V _Y , V
1.65 to 1.95	V _{CC} /2	V _{CC} /2	V _{CC} /2	0.15
2.3 to 2.7	V _{CC} /2	V _{CC} /2	V _{CC} /2	0.15
3.0 to 3.6	V _{CC} /2	V _{CC} /2	V _{CC} /2	0.3
4.5 to 5.5	V _{CC} /2	V _{CC} /2	V _{CC} /2	0.3

DEVICE ORDERING INFORMATION

Device	Packages	Specific Device Code	Pin 1 Orientation (See below)	Shipping [†]
NL17SZ08DFT2G	SC-88A	L2	Q4	3000 / Tape & Reel
NLV17SZ08DFT2G*	SC-88A	L2	Q4	3000 / Tape & Reel
NL17SZ08DFT2G-F22038**	SC-88A	L2	Q4	3000 / Tape & Reel
NL17SZ08DBVT1G	SC-74A	АН	Q4	3000 / Tape & Reel
NL17SZ08XV5T2G	SOT-553	L2	Q4	4000 / Tape & Reel
NL17SZ08XV5T2G-L22087**	SOT-553	L2	Q4	4000 / Tape & Reel
NL17SZ08P5T5G	SOT-953	E (Rotated 180° CW)	Q2	8000 / Tape & Reel
NL17SZ08P5T5G-L22088	SOT-953	E (Rotated 180° CW)	Q2	8000 / Tape & Reel
NL17SZ08MU1TCG	UDFN6, 1.45 x 1.0, 0.5P	D (Rotated 180° CW)	Q4	3000 / Tape & Reel
NL17SZ08MU3TCG	UDFN6, 1.0 x 1.0, 0.35P	P (Rotated 180° CW)	Q4	3000 / Tape & Reel

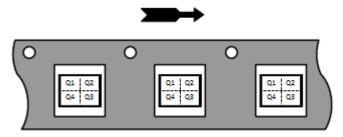
+For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

*NLV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC–Q100 Qualified and PPAP Capable.

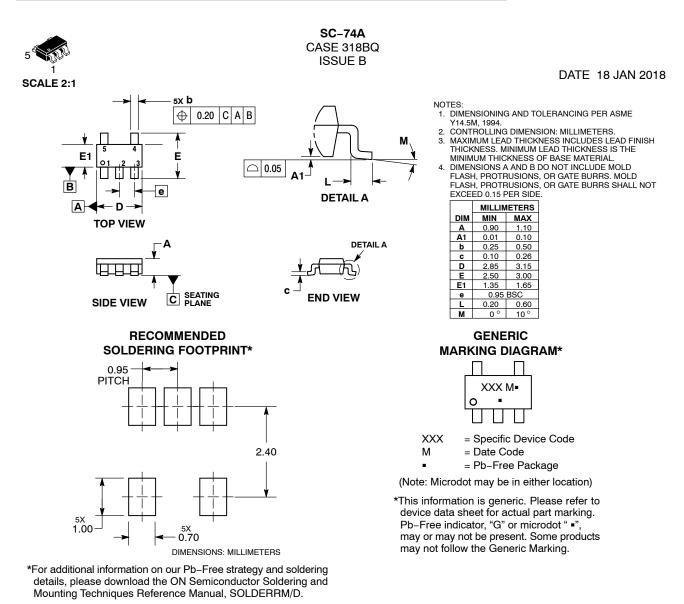
** Please refer to NLV specifications for this device.

Pin 1 Orientation in Tape and Reel

Direction of Feed

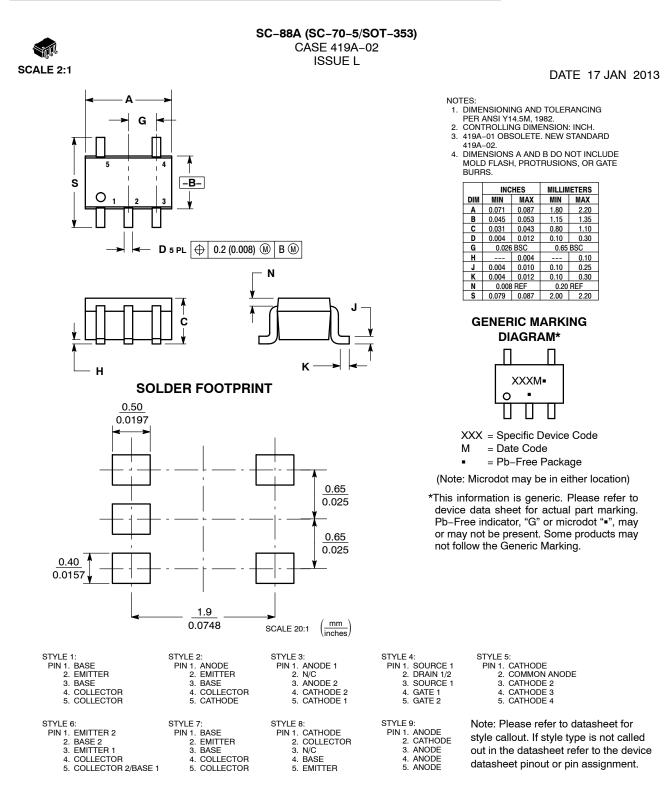






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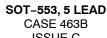
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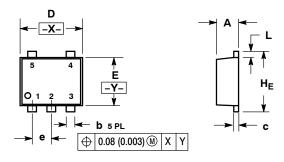




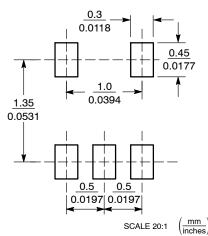
SCALE 4:1



ISSUE C



RECOMMENDED **SOLDERING FOOTPRINT***



NOTES: 1. 2.

З.

TTES: DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982. CONTROLLING DIMENSION: MILLIMETERS MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.

	MILLIMETERS			INCHES		
DIM	MIN	NOM	MAX	MIN	NOM	MAX
Α	0.50	0.55	0.60	0.020	0.022	0.024
b	0.17	0.22	0.27	0.007	0.009	0.011
c	0.08	0.13	0.18	0.003	0.005	0.007
D	1.55	1.60	1.65	0.061	0.063	0.065
Е	1.15	1.20	1.25	0.045	0.047	0.049
е	0.50 BSC				0.020 BSC)
L	0.10	0.20	0.30	0.004	0.008	0.012
ΗE	1.55	1.60	1.65	0.061	0.063	0.065

GENERIC **MARKING DIAGRAM***

XXM•

XX = Specific Device Code M = Date Code

= Pb-Free Package

(Note: Microdot may be in either location)

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot " ", may or may not be present.

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

STYLE 1:	STYLE 2:	STYLE 3:	STYLE 4:	STYLE 5:
PIN 1. BASE	PIN 1. CATHODE	PIN 1. ANODE 1	PIN 1. SOURCE 1	PIN 1. ANODE
2. EMITTER	2. COMMON ANODE	2. N/C	2. DRAIN 1/2	2. EMITTER
3. BASE	3. CATHODE 2	3. ANODE 2	3. SOURCE 1	3. BASE
4. COLLECTOR	4. CATHODE 3	4. CATHODE 2	4. GATE 1	4. COLLECTOR
5. COLLECTOR	5. CATHODE 4	5. CATHODE 1	5. GATE 2	5. CATHODE
STYLE 6:	STYLE 7:	STYLE 8:	STYLE 9:	
PIN 1. EMITTER 2	PIN 1. BASE	PIN 1. CATHODE	PIN 1. ANODE	
2. BASE 2	2. EMITTER	2. COLLECTOR	2. CATHODE	
3. EMITTER 1	3. BASE	3. N/C	3. ANODE	
4. COLLECTOR 1	4. COLLECTOR	4. BASE	4. ANODE	
5. COLLECTOR 2/BASE 1	5. COLLECTOR	5. EMITTER	5. ANODE	

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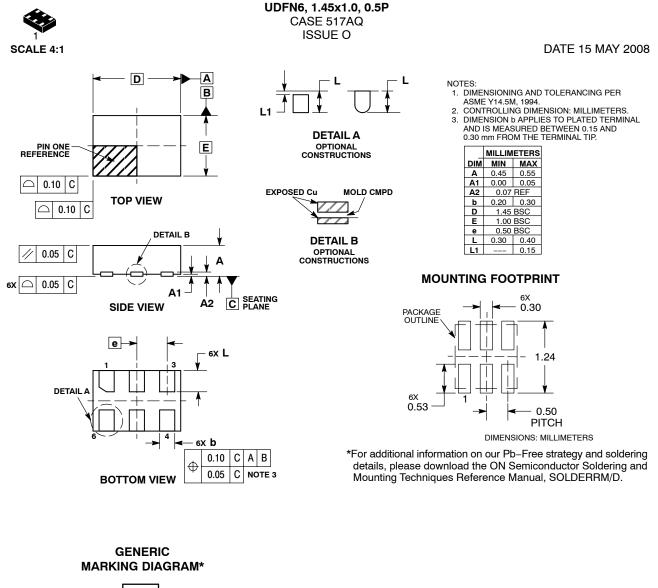
PAGE 2 OF 2

	DEV/(CION	DATE
ISSUE	REVISION	DATE
А	ADDED STYLES 3–9. REQ. BY D. BARLOW	11 NOV 2003
В	ADDED NOMINAL VALUES AND UPDATED GENERIC MARKING DIAGRAM. REQ. BY HONG XIAO	27 MAY 2005
С	UPDATED DIMENSIONS D, E, AND HE. REQ. BY J. LETTERMAN.	20 MAR 2013

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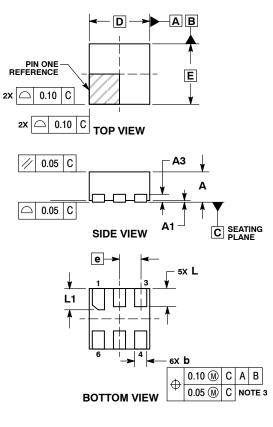
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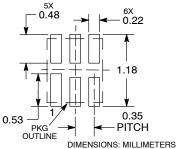
UDFN6, 1x1, 0.35P CASE 517BX ISSUE O

DATE 18 MAY 2011

- NOTES:
 DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
 CONTROLLING DIMENSION: MILLIMETERS.
 DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.20 MM FROM TERMINAL TIP.
 PACKAGE DIMENSIONS EXCLUSIVE OF BURRS AND MOLD FLASH.

BURRS AND MOLD FL						
		MILLIMETERS				
	DIM	MIN	MIN MAX			
	Α	0.45	0.55			
	A1	0.00 0.05				
	A3	0.13 REF				
	b	0.12 0.22				
	D	1.00 BSC				
	Е	1.00 BSC				
	е	0.35 BSC				
	L	0.25 0.35				
	L1	0.30	0.40			

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GENERIC **MARKING DIAGRAM***



X = Specific Device Code M = Date Code

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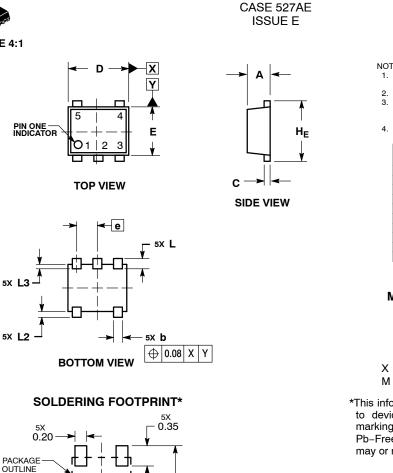
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5X L3

5X L2

0.35 PITCH





SOT-953

DATE 02 AUG 2011

NOTES: 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994. 2. CONTROLLING DIMENSION: MILLIMETERS 3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF THE BASE MATERIAL. 4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.

	MILLIMETERS			
DIM	MIN	NOM	MAX	
Α	0.34	0.37	0.40	
b	0.10	0.15	0.20	
С	0.07	0.12	0.17	
D	0.95	1.00	1.05	
Е	0.75	0.80	0.85	
e		0.35 BS	С	
ΗE	0.95	1.00	1.05	
Г		0.175 REF		
L2	0.05	0.10	0.15	
L3			0.15	

GENERIC **MARKING DIAGRAM***

= Specific Device Code

= Month Code

*This information is generic. Please refer to device data sheet for actual part marking.

Pb-Free indicator, "G" or microdot " .", may or may not be present.

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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DIMENSIONS: MILLIMETERS

1.20

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